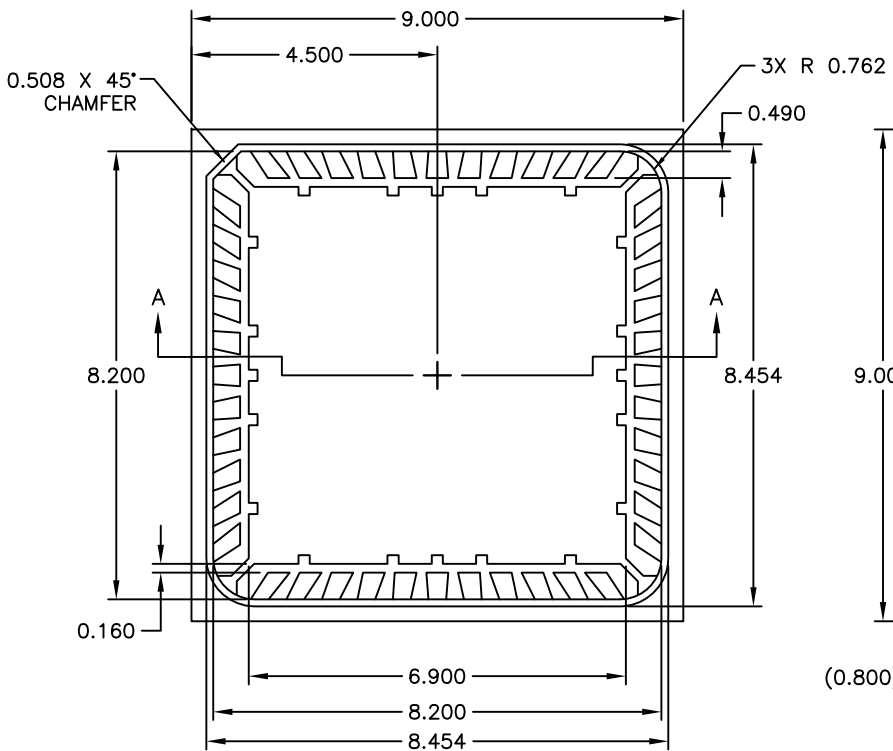
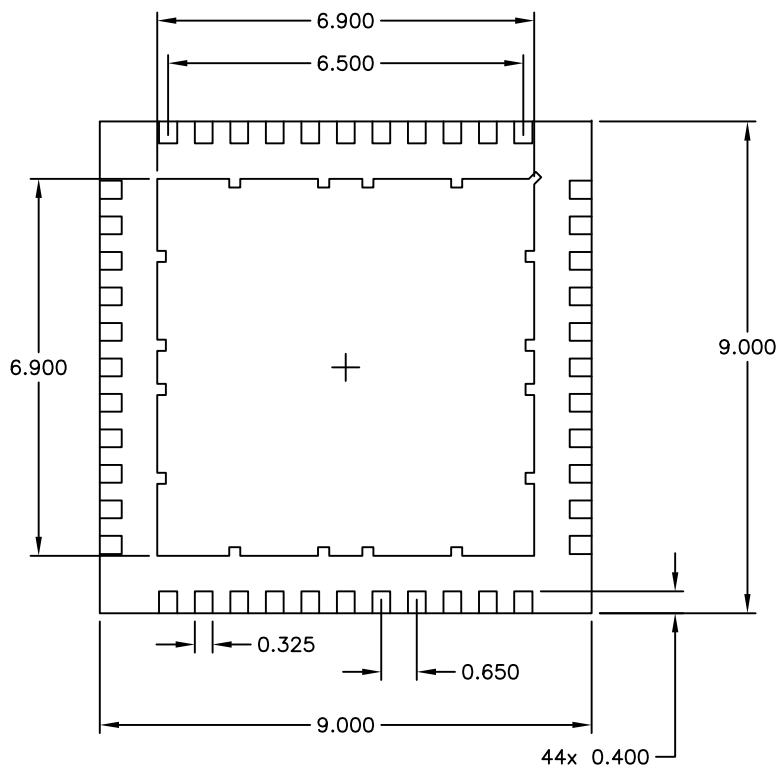
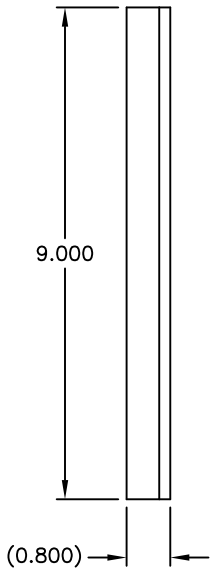


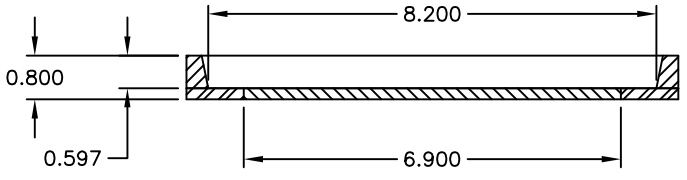
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10983	10/01/09	PRODUCTION RELEASE	D.BENANDO



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076
 5. DIE PAD: 6.900 X 6.900
 6. JEDEC OUTLINE: MO-220. (VMMC-1,2)

<p>THIRD ANGLE PROJECTION</p>	<p>DRAWN BY VSK</p>	<p>DATE 10/01/09</p>
	<p>APP BY P. FLASKERUD</p>	<p>DATE 10/01/09</p>
<p>CUSTOMER ----</p>		
<p>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:</p> <p>X.XX ± 0.15 X.XXXX ± ---</p> <p>X.XXX ± 0.100 ANGLES: ± 1°</p>		
<p>DO NOT SCALE DRAWING</p>		
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44 Lead 9mm x 9mm
MLP Open-Pak

SIZE A	PART NO. MLP9X9-44-OP-01	REV 1
SCALE NONE	CAD FILE MLP9X9-44-OP-01-R1.DWG	SHEET 1 OF 1